

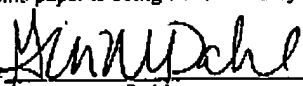
SEP 12 2005

S/N 10/826,091

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	KAWAGUCHI ET AL.	Examiner:	LAVILLA
Serial No.:	10/826,091	Group Art Unit:	1775
Filed:	APRIL 16, 2004	Docket No.:	10873.1436US01
Title:	BONDING LAYER FORMING SOLUTION, METHOD OF PRODUCING COPPER-TO-RESIN BONDING LAYER USING THE SOLUTION, AND LAYERED PRODUCT OBTAINED THEREBY		

CERTIFICATE UNDER 37 CFR 1.6(d): I hereby certify that this paper is being transmitted by facsimile to the U.S. Patent and Trademark Office on September 12, 2005.

By:   
Name: Gina M. Dahl

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Applicants elect Group I (claims 1 to 14) in response to the Restriction Requirement of August 19, 2005.

Applicants traverse the requirement to the extent of requesting that claims in Group II that correspond to allowable Group I claims be reinstated for allowance. An early and favorable action on the merits is requested.

S/N 10/826,091

PATENT


Please charge any additional fees or credit any overpayment to Deposit Account

No. 50-3478.

Respectfully submitted,

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Date: September 12, 2005

By   
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